	© Copyright 2005. I international and Pa	IPC, Bannockb	ourn, Illinois. A	ll rights reserved u ntions.	nder both	This docume level parts, t	ent is a declarat	ion of the encomp	he substance asses all low	s within the er level ma	manufactur erials for wl	er listed ite hich the m	em. Note: if anufacturer	the item is an as has engineering	ssembly with low responsibility.	
752-21.1					Form Type Distribute						eous Materia	rials and Mfg Information				
upplie	r Information															
Company name* Comp				Company unique ID			Unique ID Authority					Response Date*				
nsemi												2024-05-06				
Contact N	Jame	Title - Contact				Phone - Contact*					Email - Contact*					
Product-	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
uthorize	ed Representative*	Title - Representative				Phone - Representative*				Email - Representative*						
roduct-	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Date	e Version Manufacturing Site		ring Site	v	Veight*	UOM	Unit Type		
		FGH75T65SQD-F155 F		FS4TIGBT TO247 75A 650V			2024-05-06 CPA		5456.925		456.925	mg	Each			
Ianufa	cturing Proccess Informa	ntion														
	Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020 MS		L Rating	Peak Process Body Temperat		ure Max Time at Peak Tem		Temperatu	ire Numbe	er of Reflow Cyc	cles			
Matte Tin (Sn) - annealed C		U Alloy NA			0 C		30 seco		second	ls 3						
omments	3															
or more	information regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et						
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).							
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature	astislav Drska	Le								

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	32.0	mg	Supplier	Silicon (Si)	7440-21-3		32	mg
Die Attach Solder	35.025	mg	Supplier	Silver (Ag)	7440-22-4		0.8756	mg
			А	Lead (Pb)	7439-92-1	7a	32.3981	mg
			Supplier	Tin (Sn)	7440-31-5		1.7512	mg
lead Frame	3612.9	mg	В	Nickel (Ni)	7440-02-0		0.3613	mg
			Supplier	Iron (Fe)	7439-89-6		3.6129	mg
			Supplier	Copper (Cu)	7440-50-8		3607.8418	mg
			Supplier	Phosphorus (P)	7723-14-0		1.0839	mg
Mold Compound-Black	1740.0	mg	Supplier	Polymer(phenyl glycidil ether)-co- dicyclopentadiene	119345-05-0		87	mg
			Supplier	Proprietary	Proprietary Data		87	mg
			Supplier	Carbon Black (C)	1333-86-4		8.7	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		78.3	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1305	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		87	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		87	mg
Plating	31.0	mg	Supplier	Tin (Sn)	7440-31-5		31	mg
Wire Bond - Al	6.0	mg	Supplier	Aluminum (Al)	7429-90-5		6	mg